



### **60V N-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
60V	14mΩ @ V <sub>GS</sub> = 10V	9.5
	21mΩ @ V <sub>GS</sub> = 4.5V	7.7

### **Features and Benefits**

- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- 0.6mm Profile—Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

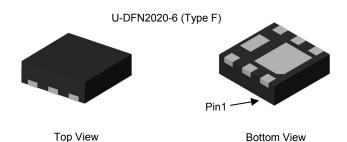
## **Description and Applications**

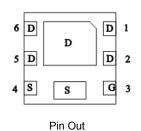
This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- DC-DC Converter
- Adaptor Switch
- · Wireless Charging

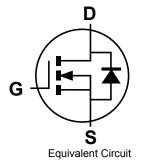
### **Mechanical Data**

- Case: U-DFN2020-6 (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—NiPdAu over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 4
- Weight: 0.007 grams (Approximate)





**Bottom View** 



## Ordering Information (Note 4)

Part Number	Package	Quantity per Reel
DMT6012LFDF-7	U-DFN2020-6 (Type F)	3000
DMT6012LFDF-13	U-DFN2020-6 (Type F)	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

Site 1:



T12 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Year	2017	201	8	2019	2020	202	21	2022	2023	202	24	2025
Code	Е	F		G	Н	I		J	K	L		М
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2:



T12 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = week 27; z represents week 52 and 53) X = Internal code (ex: U = Monday)

Date Code Key

Year	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	7	8	9	0	1	2	3	4	5
						I	I	I	ı

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z



# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		$V_{DSS}$	60	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	ΙD	9.5 7.6	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I <sub>DM</sub>	60	Α
Maximum Body Diode Continuous Current		Is	2.1	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	I <sub>SM</sub>	60	Α	
Avalanche Current (Note 7) L = 0.1mH	I <sub>AS</sub>	12.6	Α	
Avalanche Energy (Note 7) L = 0.1mH	E <sub>AS</sub>	7.9	mJ	

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Davier Dissipation (Note 5)	T <sub>A</sub> = +25°C	Б.	0.9	W
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	$P_{D}$	0.6	
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\Theta JA}$	131	°C/W
Total Davier Dissination (Note 6)	T <sub>A</sub> = +25°C	Ъ	1.9	W
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	$P_{D}$	1.2	
Thermal Resistance, Junction to Ambient (Note 6)		$R_{\Theta JA}$	66	°C/W
Total Power Dissipation (Note 6)	T <sub>C</sub> = +25°C	P <sub>D</sub>	11	W
Thermal Resistance, Junction to Case (Note 6)		R <sub>OJC</sub>	11.4	°C/W
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C

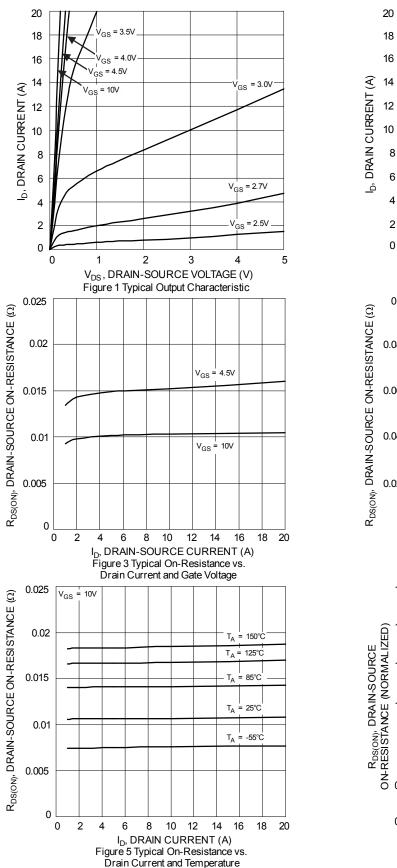
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

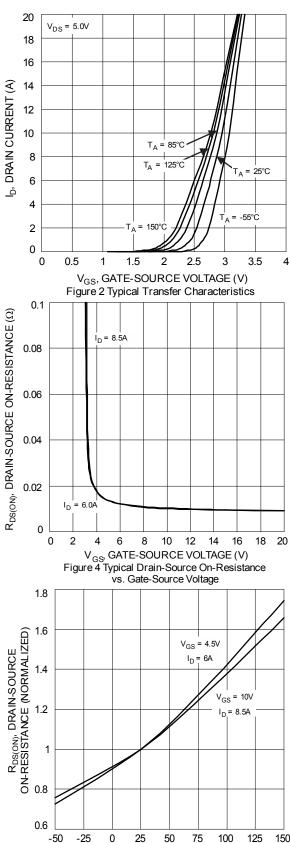
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)					•	
Drain-Source Breakdown Voltage	$BV_{DSS}$	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	$V_{DS} = 48V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.2	_	2.3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance			10.7	14	mΩ	$V_{GS} = 10V, I_D = 8.5A$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		15.7	21	11177	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6A
Diode Forward Voltage	$V_{SD}$	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss		785	_		.,
Output Capacitance	Coss		281	_	pF	$V_{DS} = 30V, V_{GS} = 0V$ f = 1MHz
Reverse Transfer Capacitance	Crss	_	27	_		1 - 1101112
Gate Resistance	$R_g$	_	1.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$	1	7.3	_		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg		13.6	_	nC	V = 20V L = 40A
Gate-Source Charge	$Q_{gs}$	_	2.2	_	IIC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 10A
Gate-Drain Charge	$Q_{gd}$		3.4	_		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.2	_		
Turn-On Rise Time	t <sub>R</sub>	_	4.4	_	ns	$V_{GS} = 10V, V_{DD} = 30V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	14.7	_	115	$R_g = 6\Omega, I_D = 10A$
Turn-Off Fall Time	t <sub>F</sub>	_	8.5	_		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	23.0	_	ns	1 - 40A di/dt - 400A/v.a
Body Diode Reverse Recovery Charge	$Q_{RR}$		14.1	_	nC	I <sub>F</sub> = 10A, di/dt = 100A/μs

5. Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout. Notes:

- 6. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
- I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
  Short duration pulse test used to minimize self-heating effect.
  Guaranteed by design. Not subject to product testing.

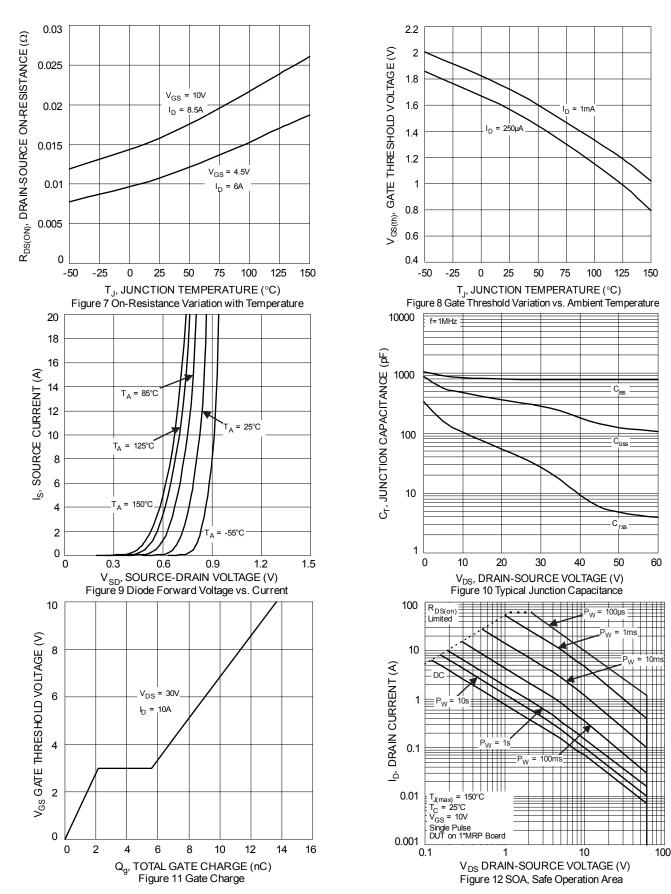




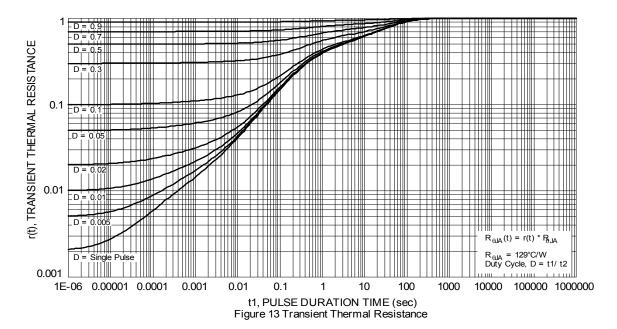


 $T_{J}, JUNCTION\ TEMPERATURE\ (°C)$  Figure 6 On-Resistance Variation with Temperature







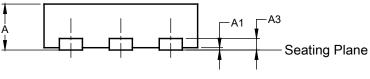


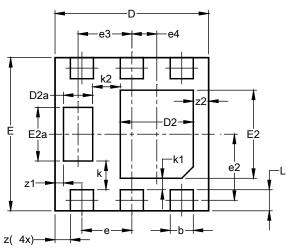


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



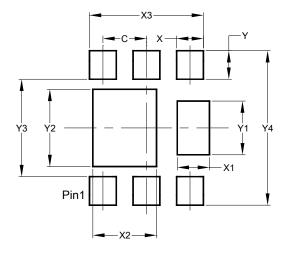


U-DFN2020-6									
	(Type F)								
Dim	Min	Max	Тур						
Α	0.57	0.63	0.60						
A1	0.00	0.05	0.03						
A3	_	_	0.15						
b	0.25	0.35	0.30						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
D2a	0.33	0.43	0.38						
Е	1.95	2.05	2.00						
E2	1.05	1.25	1.15						
E2a	0.65	0.75	0.70						
е	0.65 BSC								
e2	(	).863 BS	SC						
е3		0.70 BS	С						
e4	(	).325 BS	SC						
k		0.37 BS	С						
k1	0.15 BSC								
k2		0.36 BS							
L	0.225	0.325	0.275						
Z	0.20 BSC								
z1	0.110 BSC								
z2		0.20 BS	С						
All C	)imens	ions in	mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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